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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# MAZ9xxxH Series

## Silicon planar type

For surge absorption circuit

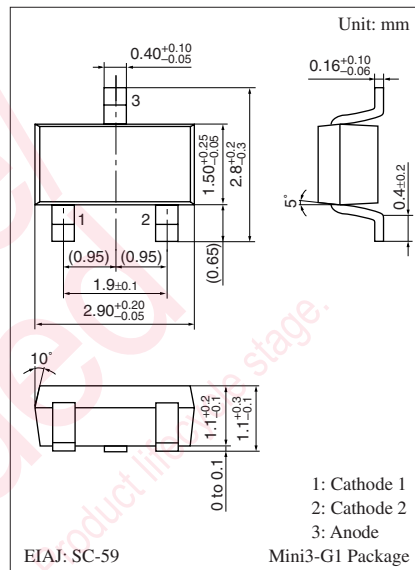
### ■ Features

- Two elements anode-common type
- Power dissipation  $P_D$  : 200 mW

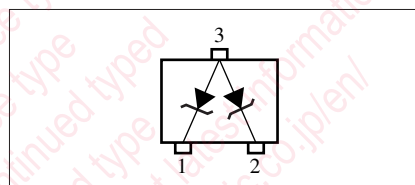
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation *	$P_D$	200	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $P_D = 200$  mW achieved with a printed circuit board.



### Internal Connection



### ■ Common Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage*	$V_Z$	$I_Z$ Specified value				V
Zener rise operating resistance	$R_{ZK}$	$I_Z$ Specified value				$\Omega$
Zener operating resistance	$R_Z$	$I_Z$ Specified value				$\Omega$
Reverse current	$I_R$	$V_R$ Specified value				$\mu\text{A}$

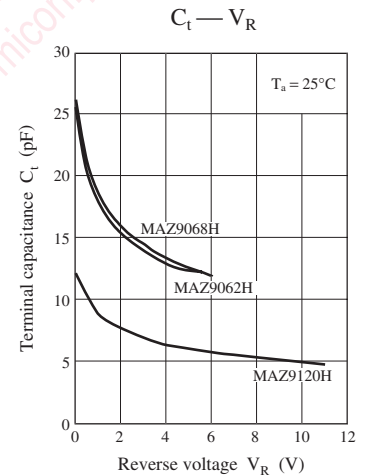
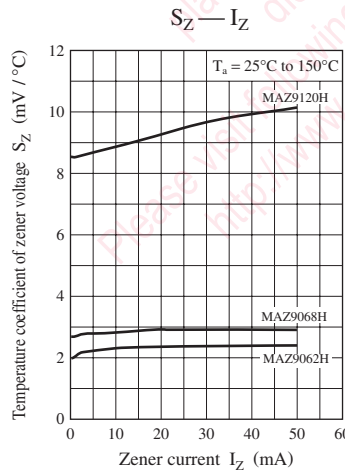
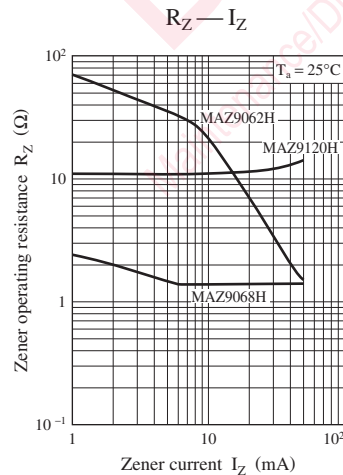
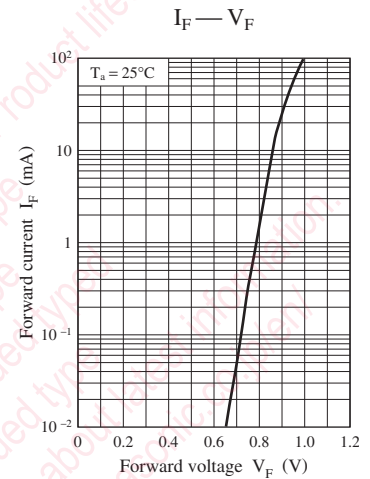
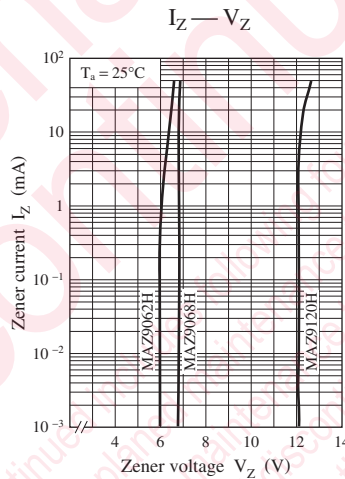
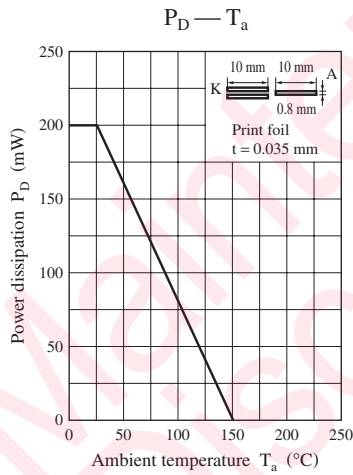
Refer to the list of the electrical characteristics within part numbers

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Electrostatic breakdown voltage:  $\pm 10$  kV  
Test method: IEC1000-4-2 (C = 150 pF, R = 330  $\Omega$ , Contact discharge: 10 times)
3. \*: The temperature must be controlled  $25^\circ\text{C}$  for  $V_Z$  measurement.  
 $V_Z$  value measured at other temperature must be adjusted to  $V_Z (25^\circ\text{C})$   
 $V_Z$  guaranteed 20 ms after current flow.

■ Electrical characteristics within part numbers  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Part number	Zener voltage				Reverse current		Zener operating resistance $R_Z$ ( $\Omega$ ) $I_Z = 5\text{ mA}$ Max	Zener rise operating resistance $R_{ZK}$ ( $\Omega$ ) $I_Z = 0.5\text{ mA}$ Max	Marking symbol
	$V_Z$ (V)				$I_R$ (mA)				
	Min	Nom	Max	$I_Z$ (mA)	Max	$V_R$ (V)			
MAZ9062H	5.8	6.2	6.6	5	0.2	4	50	100	6.2Z
MAZ9068H	6.4	6.8	7.2	5	0.1	4	30	60	6.8Z
MAZ9120H	11.4	12.0	12.7	5	0.05	9	30	80	12Z



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